PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Takaaki Noda	12/19/2012
Jie Wang	12/19/2012

RECEIVING PARTY DATA

Name:	Hitachi Kokusai Electric Inc.
Street Address:	14-1, Sotokanda 4-chome
Internal Address:	Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1018980

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13725953

OP $40.00 13725953

CORRESPONDENCE DATA

Fax Number: 3017624056
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 301-424-3640
Email: mail@usiplaw.com
Correspondent Name: Patrick J. Finnan
Address Line 1: 9801 Washingtonian Blvd.
Address Line 2: Suite 750
Address Line 4: Gaithersburg, MARYLAND 20878

ATTORNEY DOCKET NUMBER:	1022.0026C
NAME OF SUBMITTER:	Patrick J. Finnan

Total Attachments: 1
source=ExecutedAssn#page1.tif

ASSIGNMENT

For good and valuable consideration, We, Takaaki Noda, a citizen of Japan, having an address at c/o Hitachi Kokusai Electric Inc., 1, Yasuuchi 2-chome, Yatsuo-machi, Toyama-shi, Toyama 9392393, Japan, Jie Wang, a citizen of China, having an address at c/o Hitachi Kokusai Electric Inc., 1, Yasuuchi 2-chome, Yatsuo-machi, Toyama-shi, Toyama 9392393, Japan, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Hitachi Kokusai Electric Inc.**, a corporation organized and existing under the laws of Japan, having its principal place of business at 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1018980, Japan, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

entitled: **SUBSTRATE PROCESSING APPARATUS, METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE AND PROGRAM**

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: Takaaki Noda DATE: December 19, 2012
Takaaki Noda

SIGNATURE: Jie Wang DATE: December 19, 2012
Jie Wang